



PMN27UP

20 V, 5.7 A P-channel Trench MOSFET

Rev. 1 — 13 July 2011

Product data sheet

1. Product profile

1.1 General description

P-channel enhancement mode Field-Effect Transistor (FET) in a small SOT457 (SC-74) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

1.2 Features and benefits

- 1.8 V R_{DSon} rated
- Trench MOSFET technology
- Very fast switching

1.3 Applications

- Relay driver
- High-side load switch
- High-speed line driver
- Switching circuits

1.4 Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|---|-----|-----|------|------|
| V_{DS} | drain-source voltage | $T_j = 25\text{ °C}$ | - | - | -20 | V |
| V_{GS} | gate-source voltage | | -8 | - | 8 | V |
| I_D | drain current | $V_{GS} = -4.5\text{ V}; T_{amb} = 25\text{ °C}$ | [1] | - | -5.7 | A |
| Static characteristics | | | | | | |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = -4.5\text{ V}; I_D = -2.4\text{ A}; T_j = 25\text{ °C}$ | - | 27 | 32 | mΩ |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|-----------------------|------------------|
| 1 | D | drain | <p>SOT457 (TSOP6)</p> | <p>017aaa094</p> |
| 2 | D | drain | | |
| 3 | G | gate | | |
| 4 | S | source | | |
| 5 | D | drain | | |
| 6 | D | drain | | |

3. Ordering information

Table 3. Ordering information

| Type number | Package | | Version |
|-------------|---------|--|---------|
| | Name | Description | |
| PMN27UP | TSOP6 | plastic surface-mounted package (TSOP6); 6 leads | SOT457 |

4. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMN27UP | ZU |

5. Limiting values

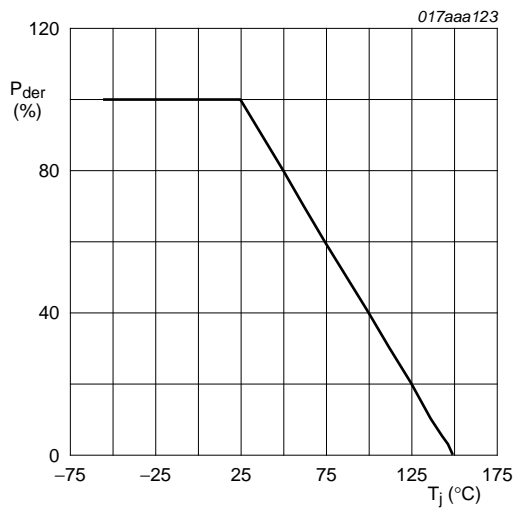
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---------------------------|-------------------------|---|-----|------|------|
| V_{DS} | drain-source voltage | $T_j = 25\text{ °C}$ | - | -20 | V |
| V_{GS} | gate-source voltage | | -8 | 8 | V |
| I_D | drain current | $V_{GS} = -4.5\text{ V}$; $T_{amb} = 25\text{ °C}$ [1] | - | -5.7 | A |
| | | $V_{GS} = -4.5\text{ V}$; $T_{amb} = 100\text{ °C}$ [1] | - | -3.5 | A |
| I_{DM} | peak drain current | $T_{amb} = 25\text{ °C}$; single pulse; $t_p \leq 10\text{ }\mu\text{s}$ | - | -23 | A |
| P_{tot} | total power dissipation | $T_{amb} = 25\text{ °C}$ [2] | - | 540 | mW |
| | | [1] | - | 1385 | mW |
| | | $T_{sp} = 25\text{ °C}$ | - | 6250 | mW |
| T_j | junction temperature | | -55 | 150 | °C |
| T_{amb} | ambient temperature | | -55 | 150 | °C |
| T_{stg} | storage temperature | | -65 | 150 | °C |
| Source-drain diode | | | | | |
| I_S | source current | $T_{amb} = 25\text{ °C}$ [1] | - | -1.5 | A |

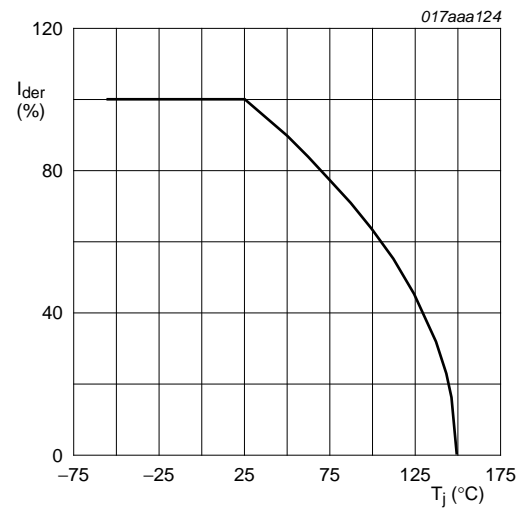
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.



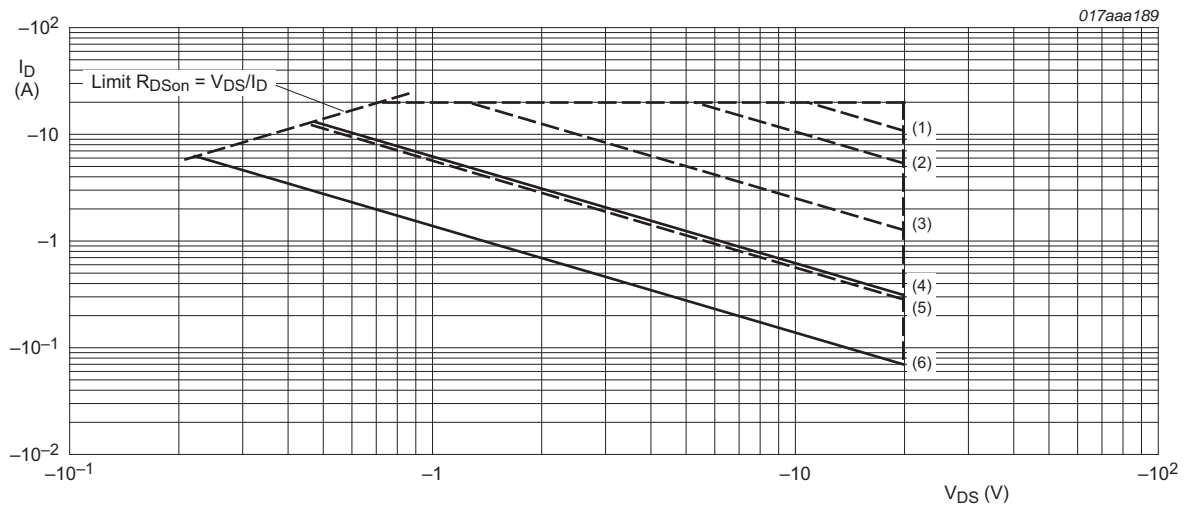
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100 \%$$

Fig 1. Normalized total power dissipation as a function of junction temperature



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100 \%$$

Fig 2. Normalized continuous drain current as a function of junction temperature



I_{DM} = single pulse

(1) $t_p = 100 \mu\text{s}$

(2) $t_p = 1 \text{ ms}$

(3) $t_p = 10 \text{ ms}$

(4) DC; $T_{sp} = 25^{\circ}\text{C}$

(5) $t_p = 100 \text{ ms}$

(6) DC; $T_{amb} = 25^{\circ}\text{C}$; drain mounting pad 6 cm^2

Fig 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

6. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|--|-------------|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] | 200 | 230 | K/W |
| | | | [2] | 78 | 90 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | - | 12 | 20 | K/W |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 6 cm².

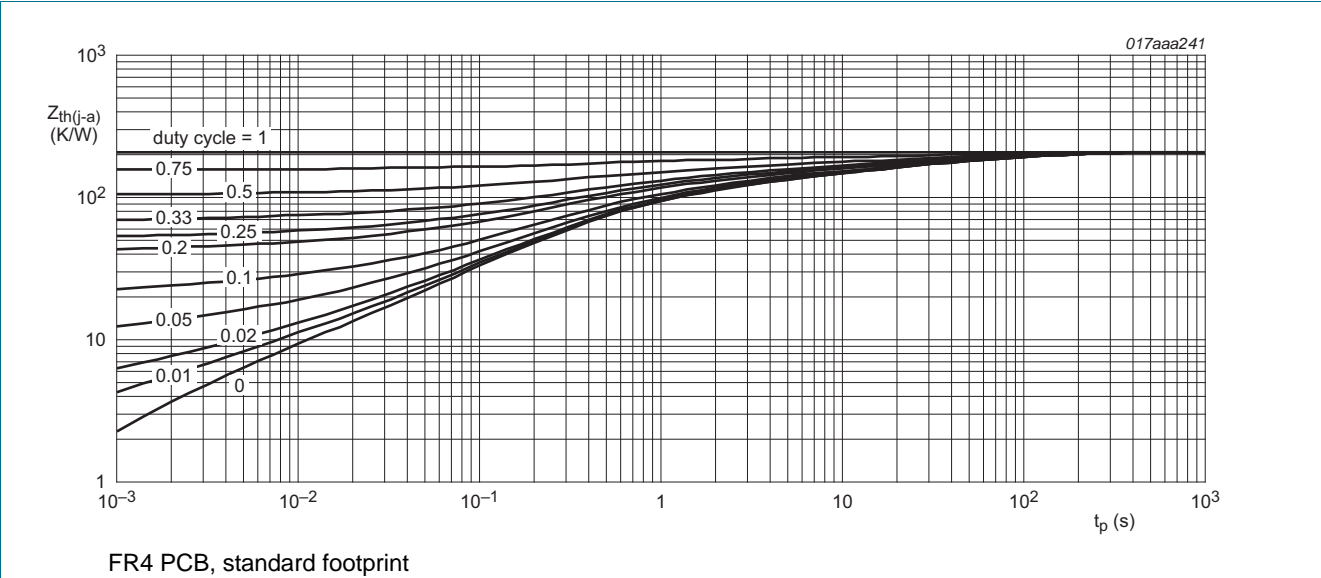


Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

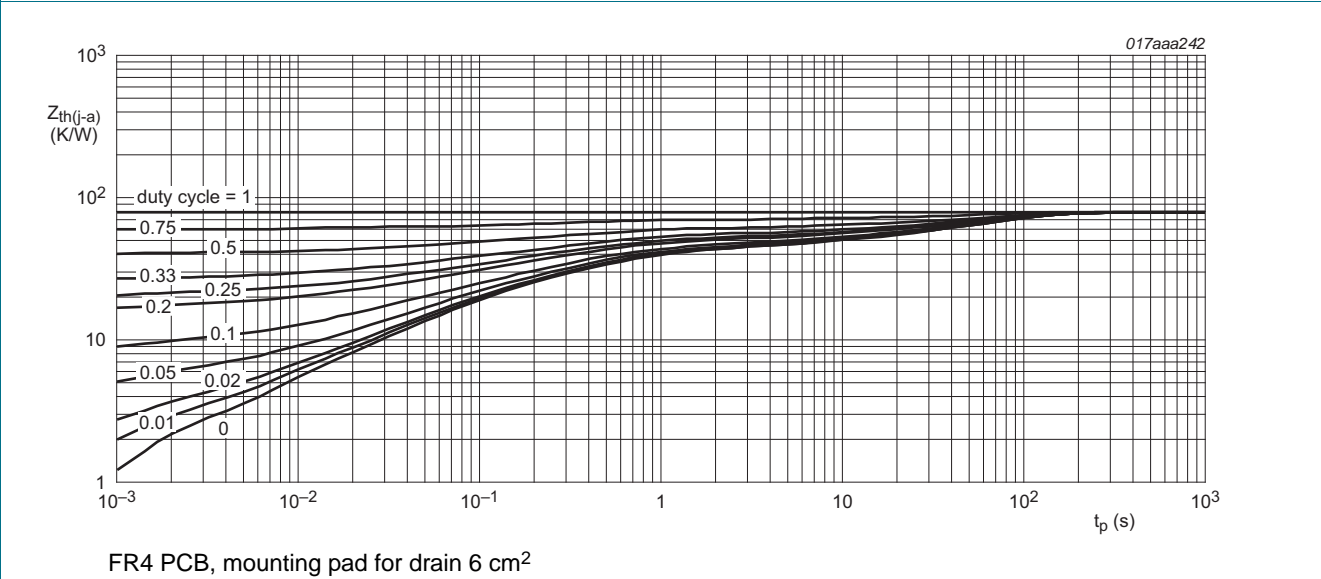


Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------|----------------------------------|---|-------|-------|-------|------|
| Static characteristics | | | | | | |
| V _{(BR)DSS} | drain-source breakdown voltage | I _D = -250 μA; V _{GS} = 0 V; T _j = 25 °C | -20 | - | - | V |
| V _{GSth} | gate-source threshold voltage | I _D = -250 μA; V _{DS} = V _{GS} ; T _j = 25 °C | -0.45 | -0.7 | -0.95 | V |
| I _{DSS} | drain leakage current | V _{DS} = -20 V; V _{GS} = 0 V; T _j = 25 °C | - | - | -1 | μA |
| | | V _{DS} = -20 V; V _{GS} = 0 V; T _j = 150 °C | - | - | -10 | μA |
| I _{GSS} | gate leakage current | V _{GS} = -8 V; V _{DS} = 0 V; T _j = 25 °C | - | - | -100 | nA |
| R _{DSon} | drain-source on-state resistance | V _{GS} = -4.5 V; I _D = -2.4 A; T _j = 25 °C | - | 27 | 32 | mΩ |
| | | V _{GS} = -4.5 V; I _D = -2.4 A; T _j = 150 °C | - | 41 | 48 | mΩ |
| | | V _{GS} = -2.5 V; I _D = -2.0 A; T _j = 25 °C | - | 36 | 41 | mΩ |
| | | V _{GS} = -1.8 V; I _D = -1.8 A; T _j = 25 °C | - | 57 | 66 | mΩ |
| g _{fs} | forward transconductance | V _{DS} = -5 V; I _D = -2.4 A; T _j = 25 °C | - | 14 | - | S |
| Dynamic characteristics | | | | | | |
| Q _{G(tot)} | total gate charge | V _{DS} = -10 V; I _D = -1 A; V _{GS} = -4.5 V; T _j = 25 °C | - | 21 | 31 | nC |
| Q _{GS} | gate-source charge | | - | 4.2 | - | nC |
| Q _{GD} | gate-drain charge | | - | 2.8 | - | nC |
| C _{iss} | input capacitance | V _{DS} = -10 V; f = 1 MHz; V _{GS} = 0 V; T _j = 25 °C | - | 2340 | - | pF |
| C _{oss} | output capacitance | | - | 210 | - | pF |
| C _{rss} | reverse transfer capacitance | | - | 150 | - | pF |
| t _{d(on)} | turn-on delay time | V _{DS} = -10 V; V _{GS} = -4.5 V; R _{G(ext)} = 6 Ω; T _j = 25 °C; I _D = -1 A | - | 19 | - | ns |
| t _r | rise time | | - | 20 | - | ns |
| t _{d(off)} | turn-off delay time | | - | 95 | - | ns |
| t _f | fall time | | - | 27 | - | ns |
| Source-drain diode | | | | | | |
| V _{SD} | source-drain voltage | I _S = -2.4 A; V _{GS} = 0 V; T _j = 25 °C | - | -0.75 | -1 | V |

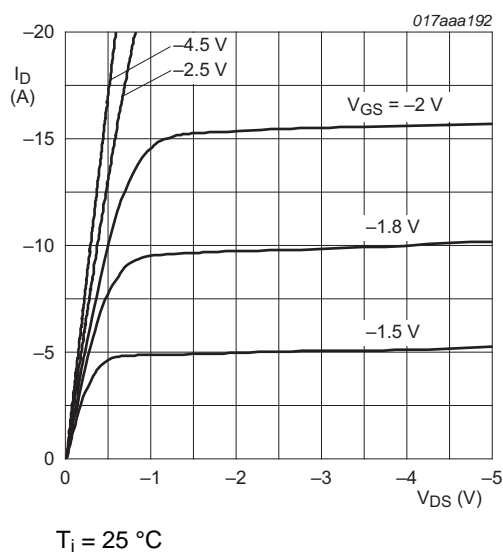


Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values

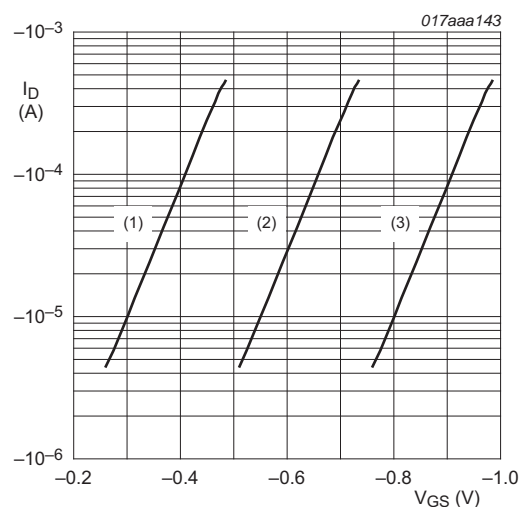


Fig 7. Sub-threshold drain current as a function of gate-source voltage

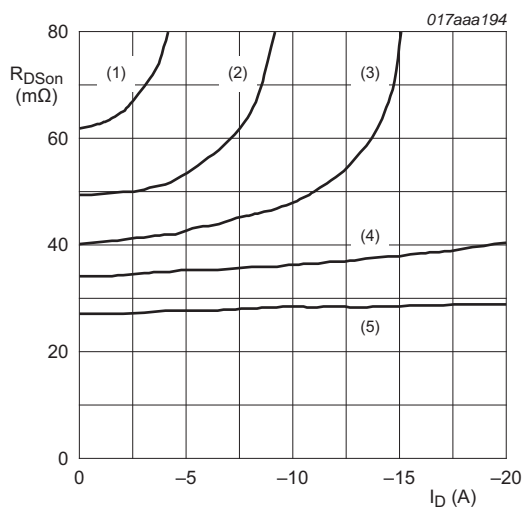


Fig 8. Drain-source on-state resistance as a function of drain current; typical values

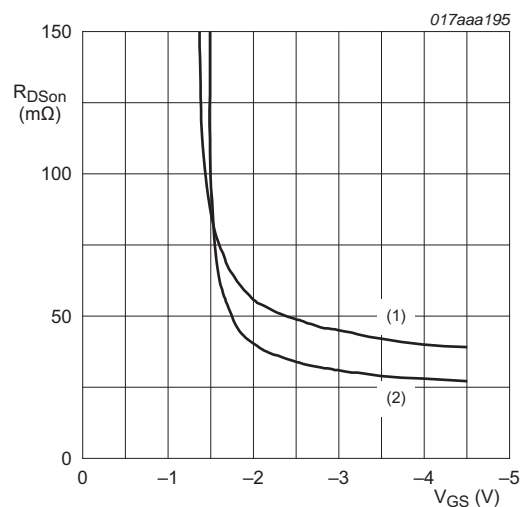
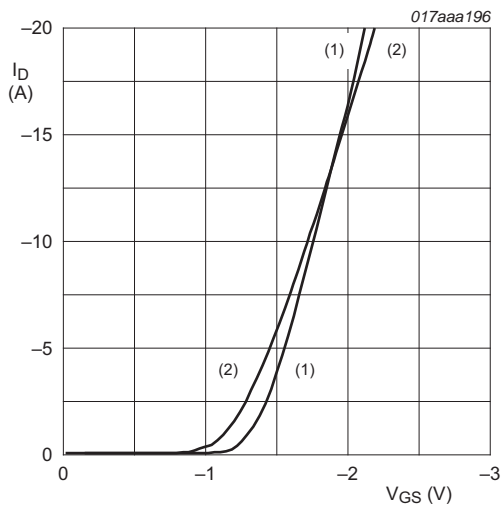


Fig 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

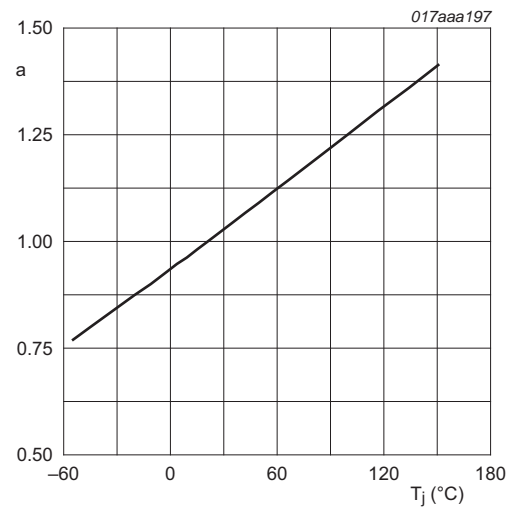


$$V_{DS} > I_D \times R_{DS(on)}$$

(1) $T_j = 25\text{ °C}$

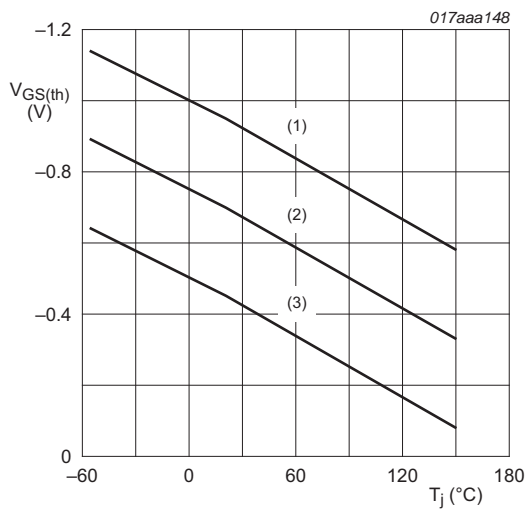
(2) $T_j = 150\text{ °C}$

Fig 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$$a = \frac{R_{DS(on)}}{R_{DS(on)(25\text{ °C})}}$$

Fig 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values



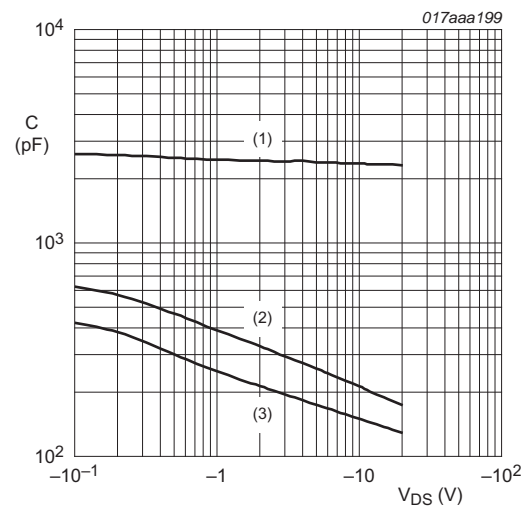
$$I_D = -0.25\text{ mA}; V_{DS} = V_{GS}$$

(1) maximum values

(2) typical values

(3) minimum values

Fig 12. Gate-source threshold voltage as a function of junction temperature



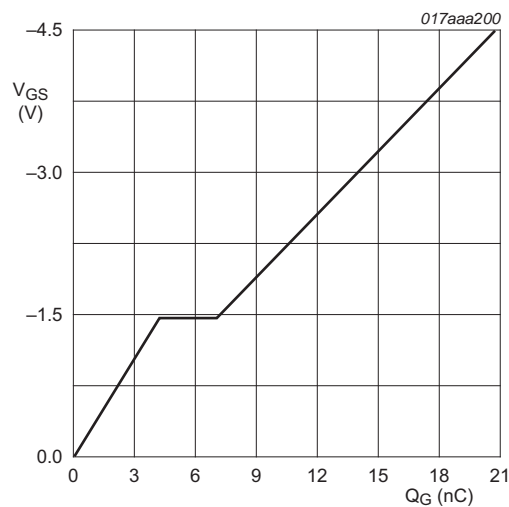
$$f = 1\text{ MHz}; V_{GS} = 0\text{ V}$$

(1) C_{iss}

(2) C_{oss}

(3) C_{rss}

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = -2.4$ A; $V_{DS} = -10$ V; $T_{amb} = 25$ °C

Fig 14. Gate-source voltage as a function of gate charge; typical values

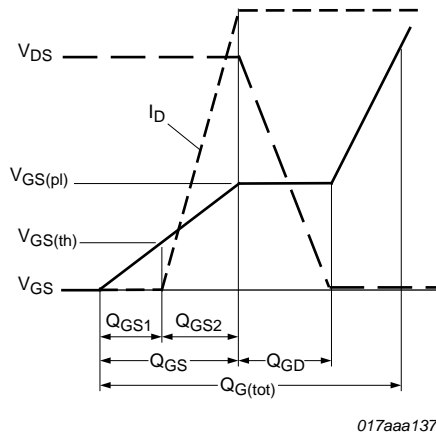
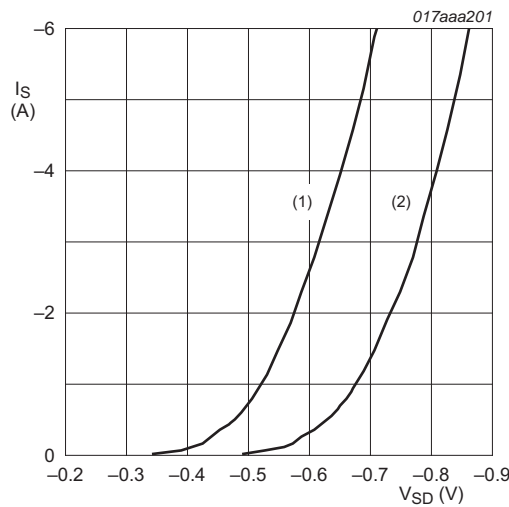


Fig 15. Gate charge waveform definitions



$V_{GS} = 0$ V
(1) $T_j = 150$ °C
(2) $T_j = 25$ °C

Fig 16. Source current as a function of source-drain voltage; typical values

8. Test information

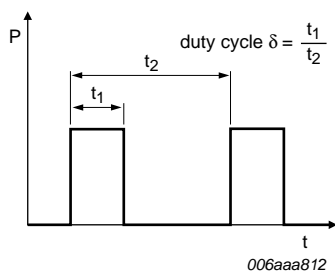


Fig 17. Duty cycle definition

9. Package outline

Plastic surface-mounted package (TSOP6); 6 leads

SOT457

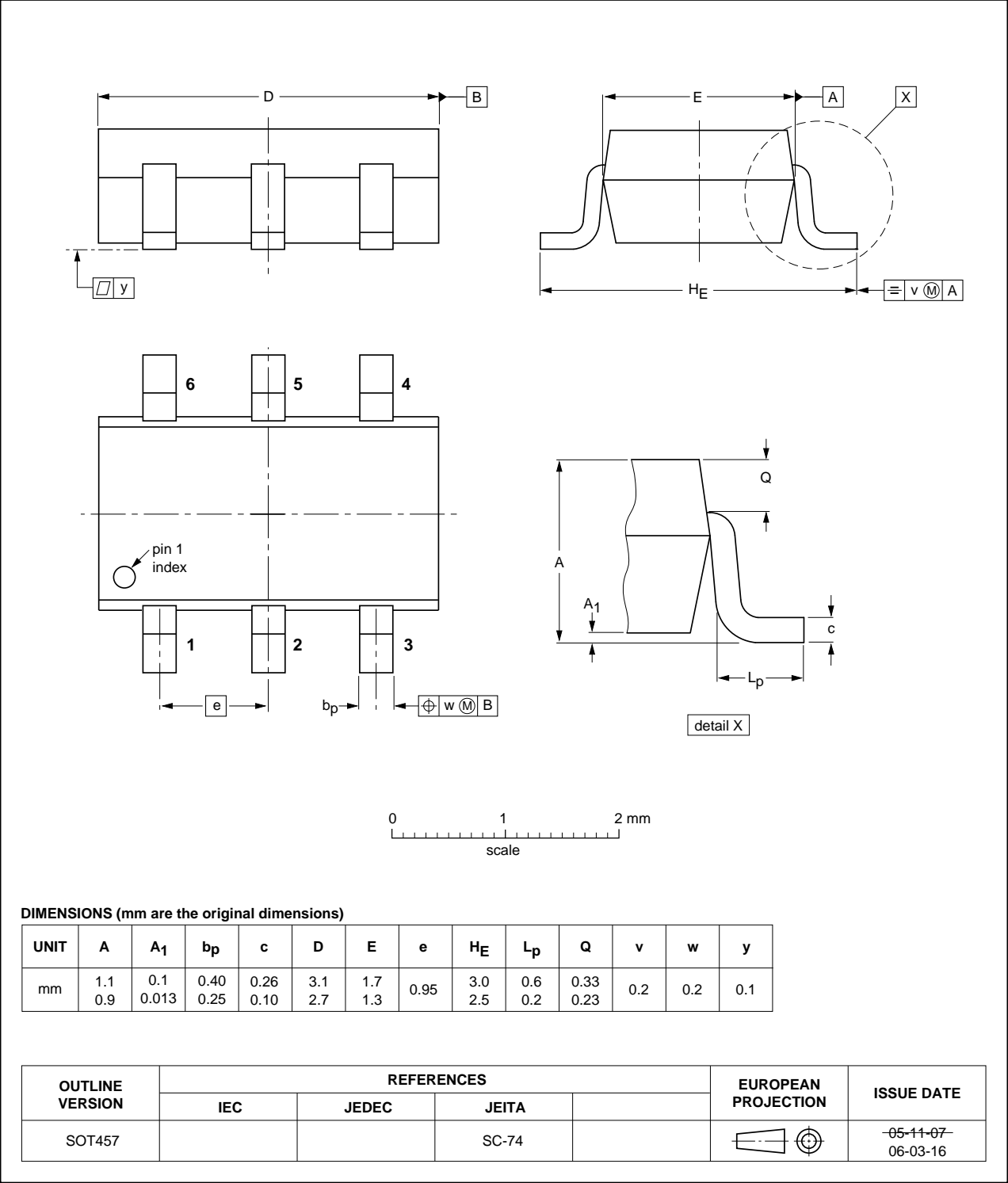
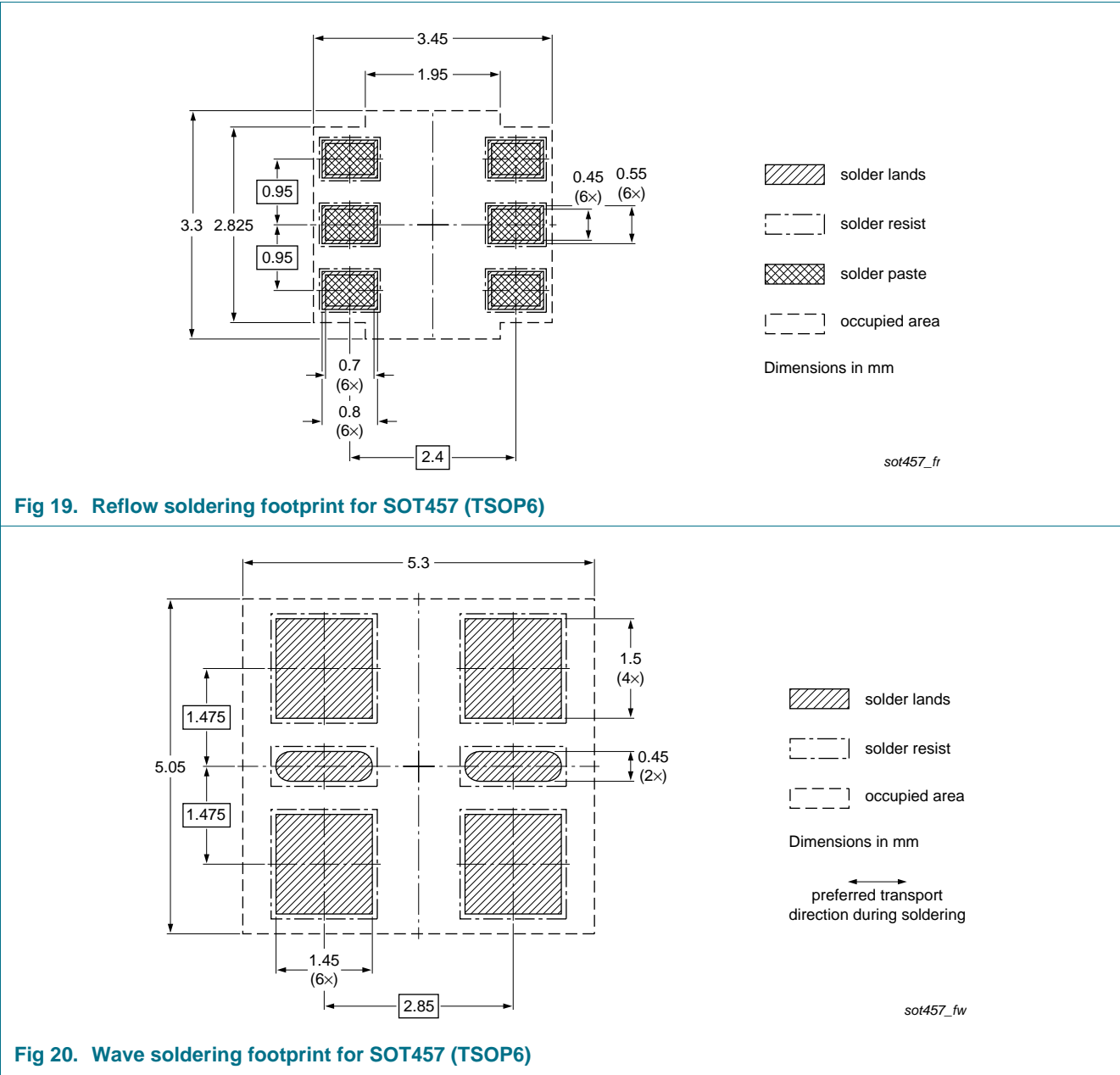


Fig 18. Package outline SOT457 (TSOP6)

10. Soldering



11. Revision history

Table 8. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-------------|--------------|--------------------|---------------|------------|
| PMN27UP v.1 | 20110713 | Product data sheet | - | - |

12. Legal information

12.1 Data sheet status

| Document status ^{[1] [2]} | Product status ^[3] | Definition |
|------------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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For sales office addresses, please send an email to: salesaddresses@nexperia.com

14. Contents

| | | |
|-----------|--|-----------|
| 1 | Product profile | 1 |
| 1.1 | General description | 1 |
| 1.2 | Features and benefits | 1 |
| 1.3 | Applications | 1 |
| 1.4 | Quick reference data | 1 |
| 2 | Pinning information | 1 |
| 3 | Ordering information | 2 |
| 4 | Marking | 2 |
| 5 | Limiting values | 2 |
| 6 | Thermal characteristics | 4 |
| 7 | Characteristics | 5 |
| 8 | Test information | 9 |
| 9 | Package outline | 10 |
| 10 | Soldering | 11 |
| 11 | Revision history | 12 |
| 12 | Legal information | 13 |
| 12.1 | Data sheet status | 13 |
| 12.2 | Definitions | 13 |
| 12.3 | Disclaimers | 13 |
| 12.4 | Trademarks | 14 |
| 13 | Contact information | 14 |